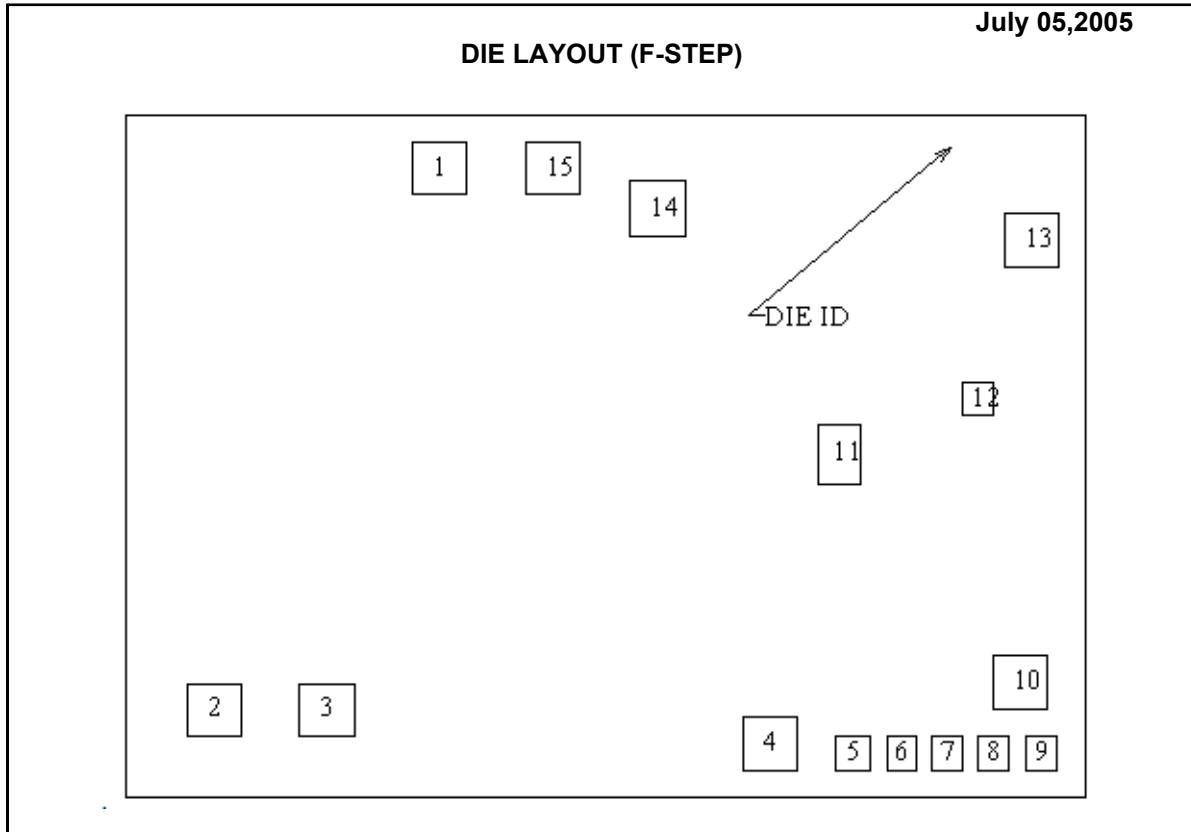


LM2940C-12 MDC MWC
1A LOW DROPOUT ADJUSTABLE REGULATOR



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM1940F	Bond Pad Opening Size (min)	140 μ m x 135 μ m
Die Step	F	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	TI,NI,AG
Die Size (Drawn)	1753 μ m x 2464 μ m 69.0mils x 97.0mils	Back Side Connection	GND
Thickness	330 μ m Nominal		
Min Pitch	118 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (F -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	XY COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
VIN	1	-427	741	140	x	135
OUTPUT	2	-1007	-652	140	x	130
OUTPUT	3	-717	-652	140	x	130
OUTPUT	4	422	-739	140	x	139
NC	5	636	-763	90	x	90
NC	6	760	-763	77	x	90
NC	7	878	-763	77	x	90
NC	8	997	-763	77	x	90
NC	9	1120	-763	77	x	90
GND	10	1063	-582	139	x	139
NC	11	601	7	109	x	153
NC	12	957	148	78	x	88
NC	13	1094	555	140	x	140
GND	14	133	637	140	x	140
VIN	15	-137	741	140	x	135

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